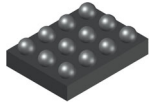


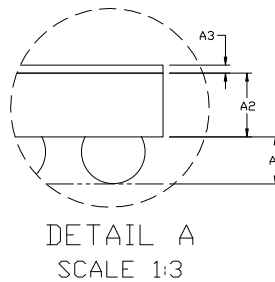
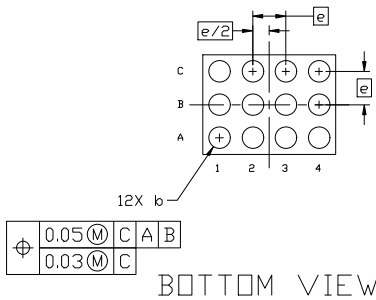
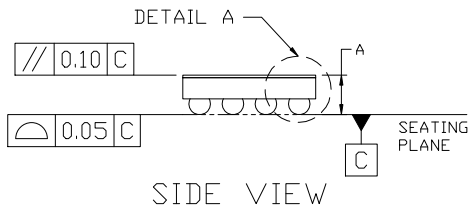
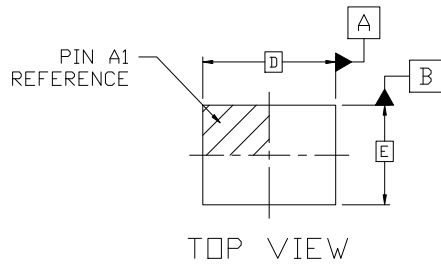
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



WLCSP12 2.00x1.50x0.596
CASE 499AZ
ISSUE A

DATE 03 JUN 2022

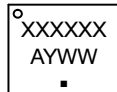


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

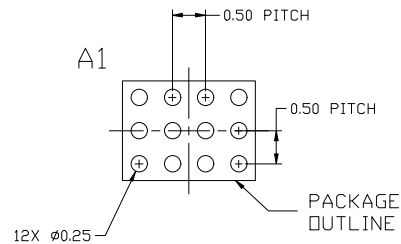
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.541	0.596	0.651
A1	0.206	0.236	0.266
A2	0.295	0.320	0.345
A3	0.04 BSC		
b	0.289	0.319	0.349
D	2.00 BSC		
E	1.50 BSC		
e	0.50 BSC		

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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DESCRIPTION:	WLCSP12 2.00x1.50x0.596	PAGE 1 OF 1

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